



5560 Solder Nu Metal Cleaner For Solder and Silver

Product Description

Kester 5560 Solder Nu Metal Cleaner is a non-fuming liquid solution for removing oxides, sulfides, carbonates and other contamination, such as etch residues, from copper metal surfaces to facilitate soldering. This stable solution cleans by dissolving or solubilizing the contamination for easy removal by water rinsing. The chemical cleaning action is quite different from strong mineral acids which etch away valuable base metal and passivate the surface by insoluble film formation. 5560 contains a pink pH indicator which turns yellow at pH 3.5 indicating the solution has lost its efficiency. 5560 is a non-foaming chemical for use in spray cleaning equipment. Because the etch rate is controlled, the bath life is very extended. 5560 will selectively remove surface contamination from solder-plated or tin-plated surfaces as well as very tarnished copper surfaces. 5560 is very effective in cleaning silver-plated surfaces with no appreciable metallic etching.

Performance Characteristics:

- Removes oxidation to facilitate soldering
- Easily cleaned in water
- Minimal etching

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

Physical Properties

Specific Gravity: 1.085 ± 0.010
Antoine Paar DMA 35 @ 25°C

pH (10% solution): 1.01
Hanna Instruments 8314 @ 25°C

Flash Point: >100°C (212°F)

Flux Application

Surfaces to be cleaned should be free of oil and grease. 5560 should be used as received in plastic or glass containers at room temperature or hot 49-60°C (120-140°F). Heating the solution accelerates the rate at which 5560 Solder-Nu reacts with contaminants. Parts are immersed for 30 seconds to 3 minutes depending on the condition of the surface and then water-rinsed to remove the solubilized contamination. Residual water-insoluble metallic complexes can be removed from an etched surface with minimal etching of the metal. Plating or etching residues can seriously affect the reliability of a soldered connection.

Cleaning

No neutralizer, saponifiers or detergents are necessary in the water wash system for complete removal of residues. It is not recommended to use high mineral content tap water. Otherwise, tap, deionized or softened water may be used for cleaning.

Storage, Handling and Shelf Life

Because this formulation is water based, it is subject to freezing. A minimum storage temperature of 4°C (40°F) is recommended. If frozen, the 5560 is easily reconstituted by stirring at room temperature. Shelf life is 2 years from date of manufacture when handled properly and held at 4-25°C (40-77°F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product.